

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method for forming a film on a substrate, comprising:
discharging a liquid material using an inkjet discharge device to the substrate to form a film on the substrate, the liquid material including a solvent and a solute, the solvent including a heterocyclic compound, the heterocyclic compound having a furan skeleton, a boiling point of the heterocyclic compound being greater than 170°C, and the solvent including a benzene derivative.

2-10. (Canceled)

11. (Previously Presented) A method of forming a film on a substrate, comprising:
discharging a liquid material using an inkjet discharge device to the substrate to form a film on the substrate, the liquid material including a solvent and a solute, the solvent including a heterocyclic compound, the heterocyclic compound having a furan skeleton, and a boiling point of the heterocyclic compound being greater than 170 degrees centigrade.

12. (Previously Presented) The method according to claim 11, the heterocyclic compound including 2,3-dihydrobenzofuran.

13. (Previously Presented) The method according to claim 11, the solvent including a benzene derivative.

14. (Previously Presented) The method according to claim 11, a vapor pressure of the solvent at room temperature being less than 10 mmHg and greater than 0.10 mmHg.

15. (Previously Presented) The method according to claim 11, the solute including a semiconductor material.
16. (Previously Presented) The method according to claim 11, the solute including a conductive material.
- 17-20. (Canceled)
21. (Previously Presented) The method according to claim 1, wherein the heterocyclic compound is benzofuran or 2,3-dihydrobenzofuran.
22. (Previously Presented) The method according to claim 11, wherein the heterocyclic compound is benzofuran or 2,3-dihydrobenzofuran.